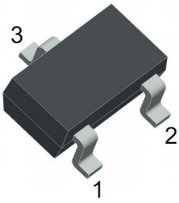
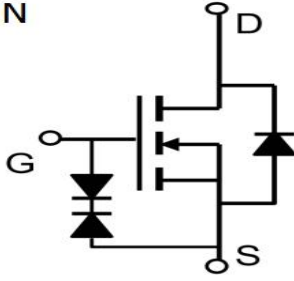
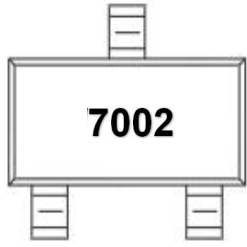


N-Channel Enhancement Mode Field Effect Transistor		SOT-23 Plastic-Encapsulate MOSFETS	
<p style="text-align: center;"><u>SOT-23</u></p>  <p><b>1.GATE 2.SOURCE 3.DRAIN</b></p> <p><b>Equivalent Circuit:</b></p> 		<p><b>Features</b></p> <ul style="list-style-type: none"> <li>※ High density cell design for low RDS(ON)</li> <li>※ Voltage controlled small signal switch</li> <li>※ Rugged and reliable</li> <li>※ High saturation current capability</li> <li>※ ESD Protected</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>※ Load Switch for Portable Devices</li> <li>※ DC/DC Converter</li> </ul> <p><b>MARKING:</b></p> 	
<b>Maximum ratings ( Ta=25°C unless otherwise noted)</b>			
<b>Parameter</b>	<b>Symbol</b>	<b>Value</b>	<b>Unit</b>
Drain-Source Voltage	<b>VDS</b>	60	V
Gate-Source Voltage	<b>VGS</b>	±20	V
Continuous Drain Current	<b>ID</b>	0.115	A
Power Dissipation	<b>PD</b>	0.225	W
Thermal Resistance from Junction to Ambient	<b>RθJA</b>	556	°C/W
Junction Temperature	<b>TJ</b>	150	°C
Storage Temperature	<b>TSTG</b>	-55~+150	°C

**MOSFET ELECTRICAL CHARACTERISTICS**

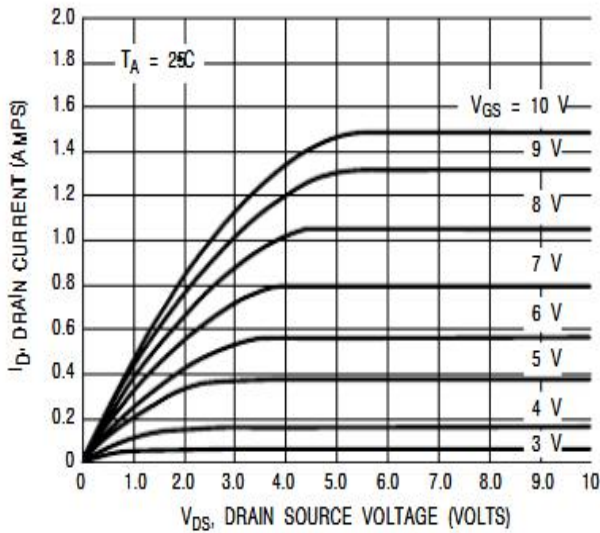
**Electrical Characteristics (Ta=25 °C unless otherwise specified)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Drain-source breakdown voltage	<b>V(BR) DSS</b>	VGS = 0V, ID =250µA	60			V
Gate threshold voltage	<b>VGS(th)</b>	VDS =VGS, ID =250µA	1		3	V
Gate-source leakage current	<b>IGSS</b>	VDS =0V, VGS =±20 V			±10	µA
Zero gate voltage drain current	<b>IDSS</b>	VDS =60V, VGS = 0V			1	µA
On-state Drain Current	<b>ID(ON)</b>	VGS =10V, VDS =7V	500			mA
Drain-source on-resistance	<b>RDS(on)</b>	VGS =10V, ID =500mA		2	5	Ω
		VGS =4.5V, ID =50mA		2.3	7	Ω
Forward tranconductance	<b>gFS</b>	VDS =10V, ID =200mA	80			mS
Drain-source on-Voitage	<b>VGS(on)</b>	VGS =10V, ID =500mA			3.75	V
		VGS =4.5V, ID =50mA			0.375	V
Dioge forward voitage	<b>VSD</b>	Is=115mA, VGS=0V	0.55		1.5	V
Input capacitance	<b>Ciss</b>	VDS =25V, VGS =0V, f =1MHz			50	pF
Output capacitance	<b>Coss</b>				25	pF
Reverse transfer capacitance	<b>Crss</b>				5	pF
Turn-on time	<b>td(on)</b>	VDD=25V,RL=50Ω, ID=500mA VGEN=10V, RG=2.7Ω			20	ns
Turn-off time	<b>td(off)</b>				40	ns

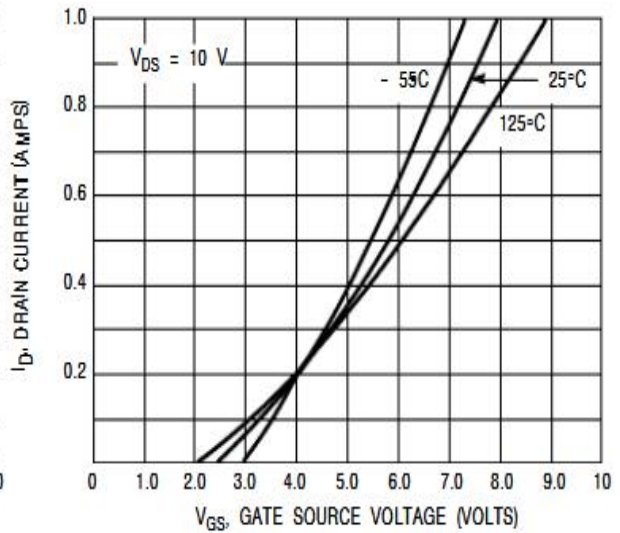
**Note :**

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t < 5 sec.
3. Pulse Test : Pulse Width≤300µs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.

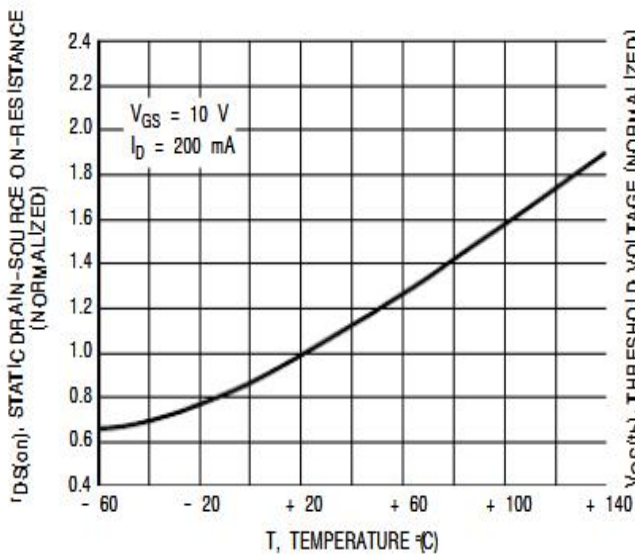
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



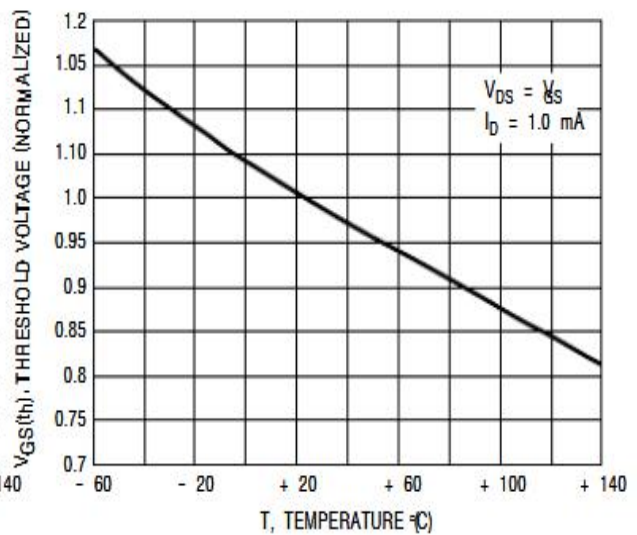
**Figure 1. Ohmic Region**



**Figure 2. Transfer Characteristics**

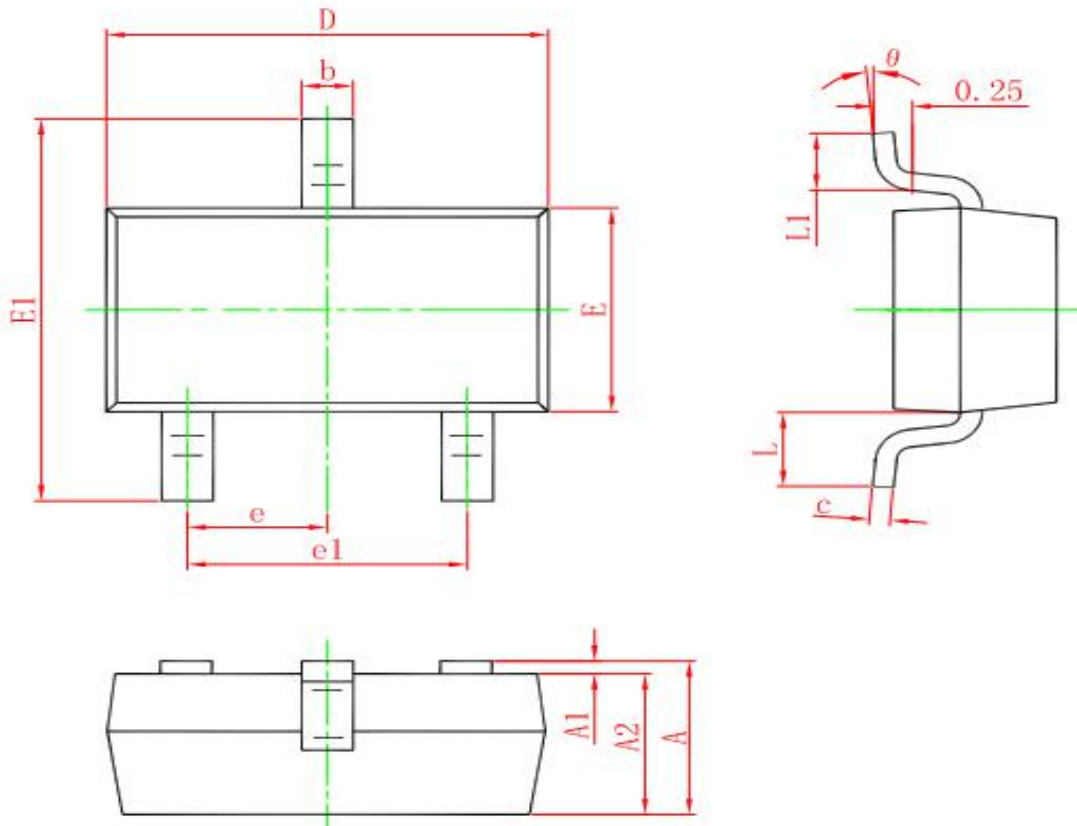


**Figure 3. Temperature versus Static Drain-Source On-Resistance**



**Figure 4. Temperature versus Gate Threshold Voltage**

**SOT-23 PACKAGE OUTLINE DIMENSIONS**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°